

**Amendments to the Claims:** This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

1. (Original) A module component comprising:
  - a substrate;
  - a partition formed on the substrate, the partition having a predetermined height to divide the substrate into a plurality of circuit blocks;
  - a sealing member covering the plurality of circuit blocks; and
  - a conductive film covering at least a surface of the sealing member, wherein the plurality of circuit blocks are electrically shielded individually.
2. (Original) The module component according to claim 1, wherein the substrate is made of resin;
  - the partition is made of resin and conductive material; and
  - the sealing member and the partition contain a same resin.
3. (Original) The module component according to claim 1, wherein the substrate is ceramic;
  - the partition is made of ceramic powder-containing resin and conductive material; and
  - the sealing member and the partition contain a same resin.
4. (Original) The module component according to claim 1, wherein the partition is a metal foil.
5. (Original) The module component according to claim 2, wherein the conductive material of the partition is a conductive resin.
6. (Original) The module component according to claim 1, wherein the partition is resin having a metal film formed on an outer surface thereof, and has a square cross section in a longitudinal direction.

7. (Original) The module component according to claim 1, wherein  
the partition is resin having a metal film formed on an outer surface thereof, and  
has a cross section with a protruding base in a longitudinal direction.
8. (Original) The module component according to claim 1, wherein  
the partition has a conductive wall in a direction vertical to the substrate.
9. (Original) The module component according to claim 1, wherein  
the partition is formed by stacking at least one metal film and resin, and  
the metal film is formed to be parallel with the longitudinal direction of the  
partition and to be vertical to the substrate.
10. (Original) The module component according to claim 1, wherein  
the partition has resin at least one side surface thereof.
11. (Original) The module component according to claim 1, wherein  
the partition is positioned inside the substrate, and has a planar shape of one of a  
circle and a polygon.
12. (Original) The module component according to claim 11, wherein  
the partition is positioned out of contact with an outer edge of the substrate.
13. (Original) The module component according to claim 1, wherein  
the partition has a planar shape of a letter T.
14. (Original) The module component according to claim 1, wherein  
the conductive film is one of metal and conductive resin.
15. (Original) The module component according to claim 1, wherein  
the partition is higher than an electric component mounted on the substrate.
16. (Original) The module component according to claim 1, wherein  
the substrate has a ground pattern on a surface thereof, and the ground pattern  
is connected with the conductive film.

17. (Currently Amended) A method for manufacturing a circuit module component having a plurality of circuit blocks shielded individually, the method comprising:
  - a first step of mounting a partition higher than the mounting components, the partition dividing mounting components and a substrate into a plurality of circuit blocks on the substrate,;
  - a second step of forming a sealing member covering the plurality of circuit blocks individually in such a manner as to be higher than the mounting components; and
  - a third step of forming a conductive film on a surface of the sealing member.
18. (Original) The method for manufacturing the module component according to claim 17, wherein
  - the partition contains a conductive material formed in a direction vertical to the substrate, and
  - the second step includes a step of polishing the sealing member so as to expose the conductive material on a surface.
19. (Original) The method for manufacturing the module component according to claim 17 further comprising:
  - a step of removing the conductive material formed in a top of the partition by one of dicing and laser.
20. (Original) The method for manufacturing the module component according to claim 17, wherein
  - the third step includes a step of connecting the conductive film with a ground pattern.